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Application No. 10/537729 Response to the Office Action dated July 21, 2008

Amendments to the Specification:

This listing of the paragraphs of the specification will replace all prior versions of the corresponding paragraphs of the specification in the application.

HSML (HM)

Listing of Amended Paragraphs of the Specification:

Please amend the paragraph beginning on page 7, lines 14 to read as follows:

The case 2 is made of a synthetic resin and has a lower surface on which the substrate 8 is mounted. As shown in Fig. 2, the case 2 includes a first space 21 for accommodating the light source unit 1. As shown in Figs. 2-4, the case 2 further includes a second space 22 for accommodating the sensor IC chips 7, and a third space 23 for accommodating the light guide 3 and the reflector 4. The first space 21 and the second space 22 are separated by a first partition wall 24 of the case 2 (See Fig. 2). The second space 22 ad and the third space 23 are separated by a second partition wall 25 (See Figs. 2 and 3). The second partition wall 25 is spaced from the substrate 8 and provided above the substrate. The first and the second partition walls 24 and 25 are provided to block the light directly traveling toward the sensor IC chips 7 from the light source unit 1. As shown in Fig. 3, the second partition wall 25 has a flat surface 25a extending parallel to the principal surface 81 of the substrate 8. The wire W enters between the flat surface 25a and the principal surface 81 of the substrate 8 at least partially.